IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

Claims 1 - 12 (cancelled)

13. (currently amended) A lead-free solder alloy ~~as claimed in claim 12 wherein the content of Ni is~~ consisting of 0.1 - 3 wt% of Cu, 0.001 - 0.1 wt% of P, greater than 0 and at most 0.3 wt % of Ni, and a balance of Sn.

14. (currently amended) A lead-free solder alloy as claimed in claim ~~12~~ 13 wherein the content of P is 0.001 - 0.05 wt%.

15. (currently amended) A lead-free solder alloy as claimed in claim ~~12~~ 13 wherein the content of P is 0.001 - 0.01 wt%.

16. (currently amended) A solder paste comprising the lead-free solder alloy of claim ~~12~~ 13.

17. (currently amended) A flow soldered joint connected to an electronic component and formed by flow soldering with a lead-free solder alloy as claimed in claim ~~12~~ 13.

18. (currently amended) A soldering method comprising forming a bath of molten solder of the lead-free solder alloy as claimed in claim ~~12~~ 13 and contacting ~~an object to be soldered~~ an electronic component with the molten solder.

19. (currently amended) A method as claimed in claim 18 including contacting the ~~object~~ electronic component with a wave of the molten solder.

Claims 20 - 31 (cancelled)

32. (new) A flow soldered joint as claimed in claim 17 which connects the electronic component to a printed wiring board.

33. (new) A method as claimed in claim 18 wherein the electronic component is disposed on a printed wiring board while contacting the molten solder.

34. (new) A soldering method comprising forming a bath of a molten lead-free solder alloy consisting of 0.1 - 3 wt% of Cu, 0.001 - 0.1 wt% of P, greater than 0 and at most 0.5 wt% of Ni, and a balance of Sn, and contacting an electronic component disposed on a printed wiring board with the molten solder.

35. (new) A method as claimed in claim 34 including contacting the electronic component with a wave of the molten

solder.

36. (new) A flow soldered joint formed by the method claimed in claim 34 connecting the printed wiring board and the electronic component of claim 34.